Abstracts

Silicon substrate coupling noise modeling, analysis, and experimental verification for mixed signal integrated circuit design

W. Jin, Y. Eo, J.I. Shim, W.R. Eisenstadt, M.Y. Park and H.K. Yu. "Silicon substrate coupling noise modeling, analysis, and experimental verification for mixed signal integrated circuit design." 2001 MTT-S International Microwave Symposium Digest 01.3 (2001 Vol. III [MWSYM]): 1727-1730 vol.3.

The frequency-variant characteristics of a silicon substrate were physically modeled, analytically investigated, and experimentally verified. The scalable circuit model parameter extraction methodology was newly developed. Thus, the proposed technique can provides the efficient performance evaluations as well as the accurate design guidelines concerned with the complicated mixed signal integrated circuit designs.

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